

CMOS-CCD 1H Delay Line for PAL

Description

The CXL5514M/P are CMOS-CCD delay line ICs designed for processing video signals. This ICs provide a 1H delay time for PAL signals including the external lowpass filter.

Features

- Single 5V power supply
- Low power consumption
- Built-in peripheral circuit
- Built-in tripling PLL circuit
- Sync tip clamp mode

Absolute Maximum Ratings (Ta = 25°C)

• Supply voltage	V _{DD}	+6	V
• Operating temperature	Topr	−10 to +60	°C
• Storage temperature	Tstg	−55 to +150	°C
• Allowable power dissipation	P _D		
	CXL5514M	350	mW
	CXL5514P	480	mW

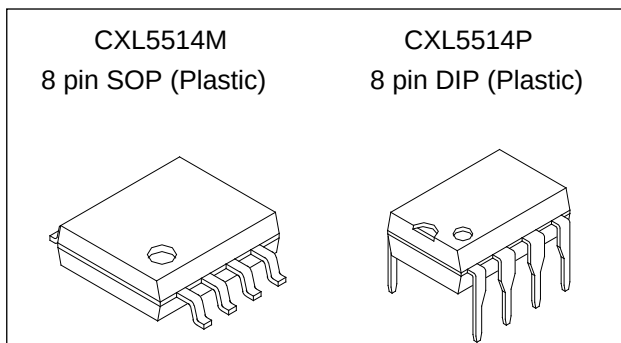
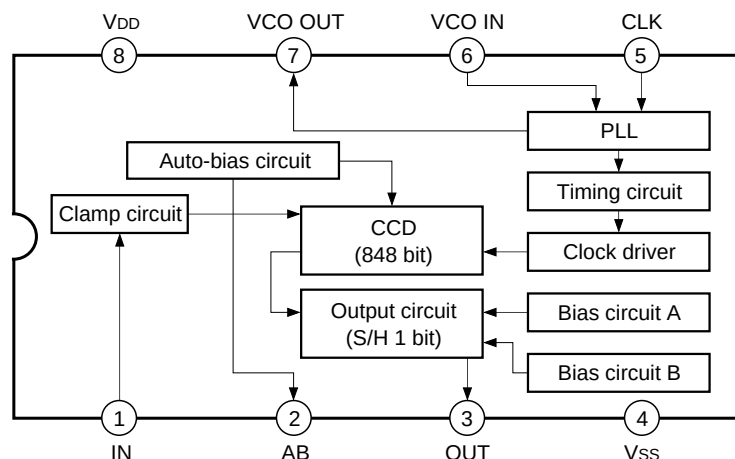
Recommended Operating Range (Ta = 25°C)

V_{DD} 5V ± 5%

Recommended Clock Conditions (Ta = 25°C)

- Input clock amplitude
V_{CLK} 0.2 to 1.0Vp-p (0.4Vp-p Typ.)
- Clock frequency
f_{CLK} 4.433619MHz
- Input clock waveform Sine wave

Block Diagram and Pin Configuration (Top View)



Input Signal Amplitude

V_{sig} 500mVp-p (Typ.), 575mVp-p (Max.)
(at internal clamp condition)

Functions

- 848-bit CCD register
- Clock driver
- Auto-bias circuit
- Sync tip clamp circuit
- Sample and hold circuit
- Tripling PLL circuit
- Inverted output

Structure

CMOS-CCD

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Pin Description

Pin No.	Symbol	I/O	Description	Impedance
1	IN	I	Signal input	>10K Ω
2	AB	O	Auto-bias DC output	
3	OUT	O	Signal output	40 to 500 Ω
4	V _{SS}	—	GND	
5	CLK	I	Clock input (fsc)	>10K Ω
6	VCO IN	I	VCO input	
7	VCO OUT	O	VCO output (3fsc)	
8	V _{DD}	—	5V power supply	

Electrical Characteristics

(Ta = 25°C, V_{DD} = 5V, f_{CLK} = 4.433619MHz, V_{CLK} = 400mVp-p, sine wave)

See "Electrical Characteristics Test Circuit".

Item	Symbol	Conditions	SW conditions		Min.	Typ.	Max.	Unit	NOTE
			1	2					
Supply current	I _{DD}	—	a	—	10	15	20	mA	1
Low frequency gain	GL	200kHz 500mVp-p Sine wave	a	b	−2	0	2	dB	2
Frequency response	f _R	200kHz ↔ 4.434MHz 150mVp-p Sine wave	b ↔ c	b	−2.7	−1.7	−0.7	dB	3
Differential gain	DG	5-staircase wave (See Note 4.)	d	c	0	3	5	%	4
Differential phase	DP	5-staircase wave (See Note 4.)	d	c	0	3	5	degree	4
S/H pulse coupling	CP	No signal input	f	a	—	—	350	mVp-p	5
S/N ratio	SN	50% white video signal (See Note 6.)	e	d	52	56	—	dB	6

NOTE

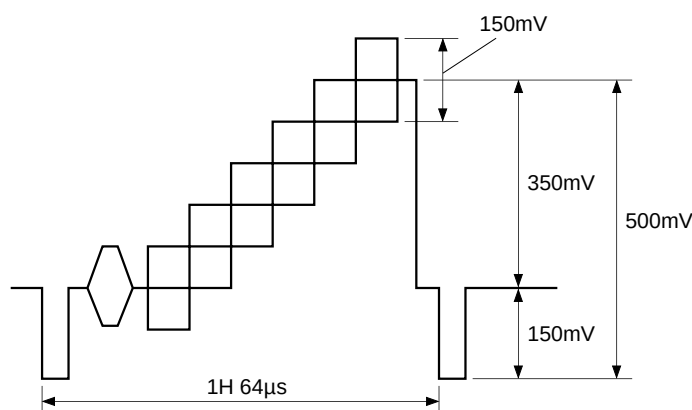
1. This is the IC supply current value during clock and signal input.
2. GL is the output gain of OUT pin when a 500mVp-p, 200kHz sine wave is fed to IN pin.

$$GL = 20 \log \frac{\text{OUT pin output voltage [mVp-p]}}{500 \text{ [mVp-p]}} \text{ [dB]}$$

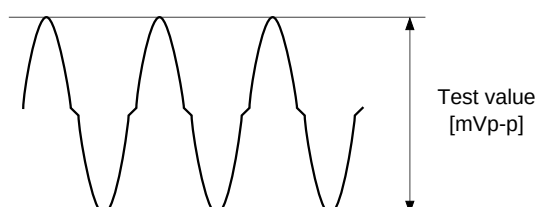
3. Indicates the dissipation at 4.434MHz in relation to 200kHz. From the output voltage at OUT pin when a 150mVp-p, 200kHz sine wave is fed to IN pin, and from the output voltage at OUT pin when a 150mVp-p, 4.434MHz sine wave is fed to the same, calculation is made according to the following formula.

$$f_R = 20 \log \frac{\text{OUT pin output voltage (4.434MHz) [mVp-p]}}{\text{OUT pin output voltage (200kHz) [mVp-p]}} \text{ [dB]}$$

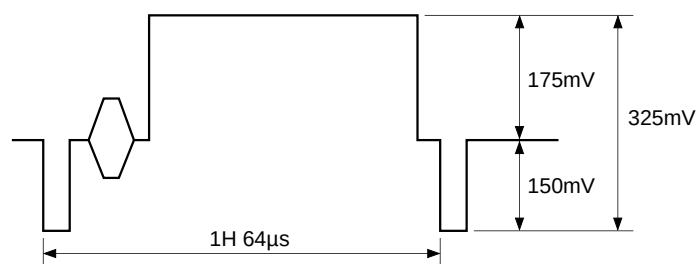
4. In Fig. below, the differential gain (DG) and the differential phase (DP) are tested with a vector scope when the 5-staircase wave is fed.



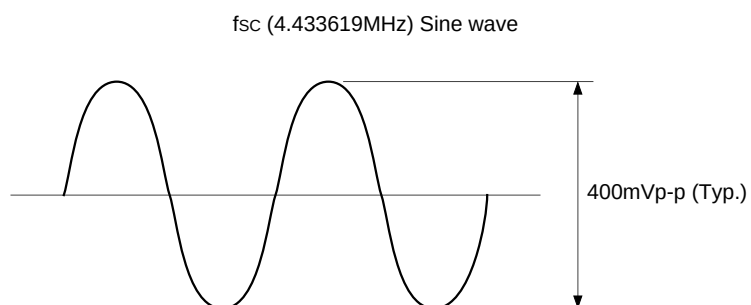
5. Leakage of internal clock components and related high frequency component to the output signal, during no signal input, is tested.



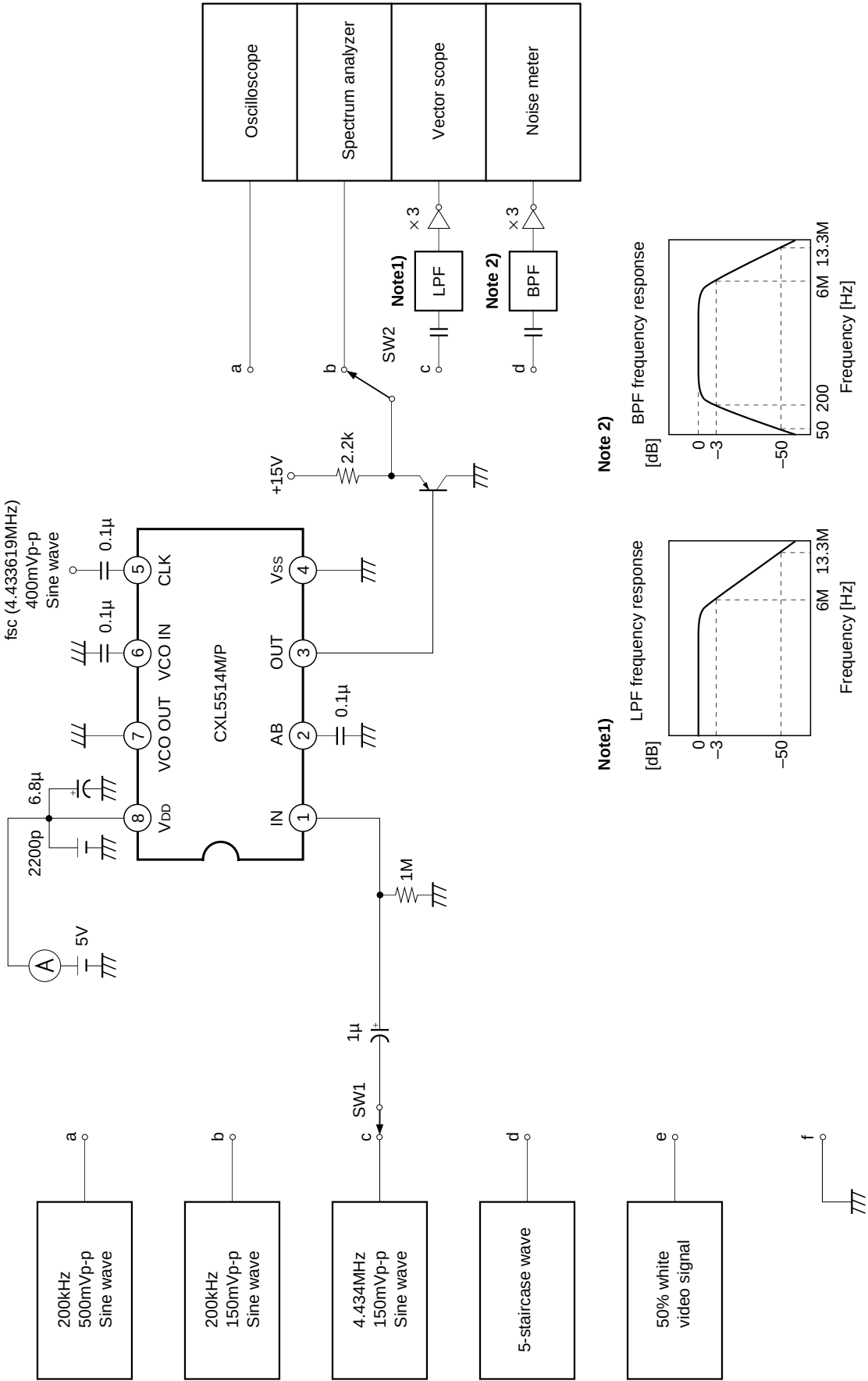
6. S/N ratio during a 50% white video signal input shown in Fig. below is tested at the video noise meter, in BPF 100kHz to 5MHz, Sub Carrier Trap mode.



CLOCK

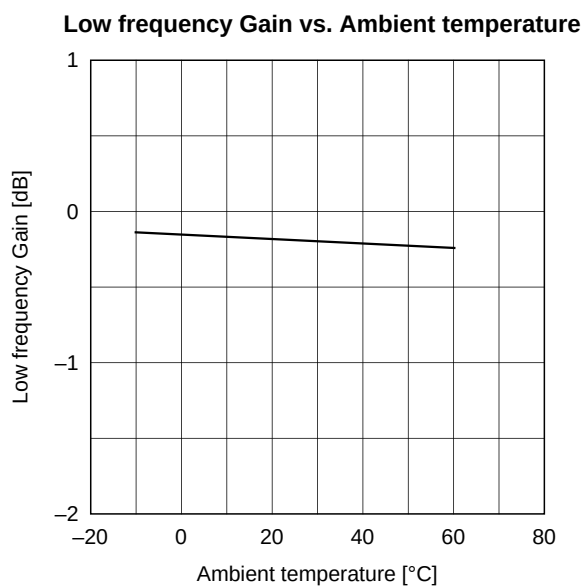
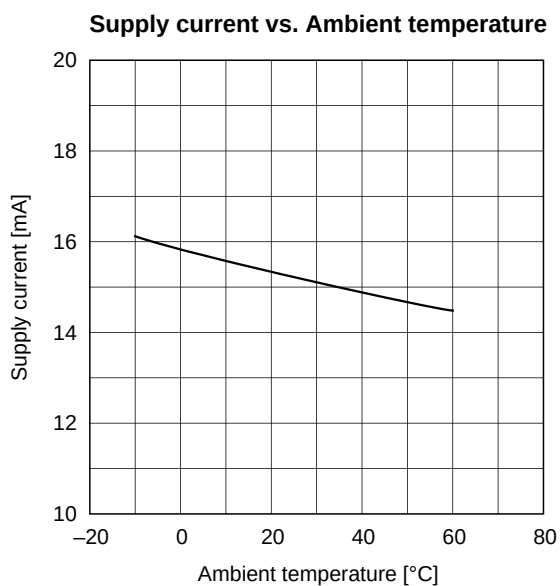
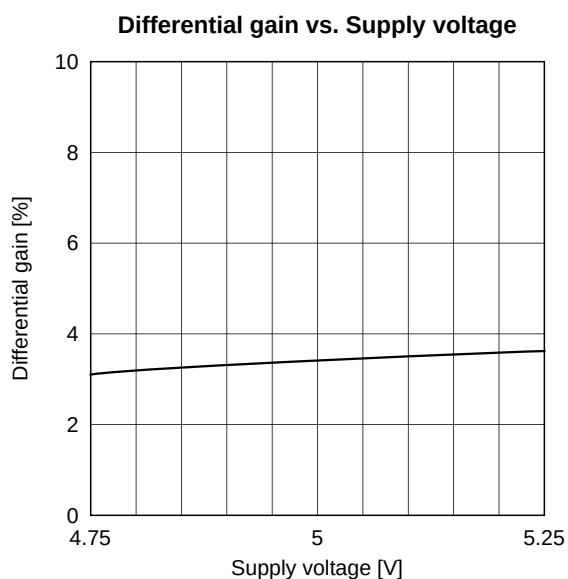
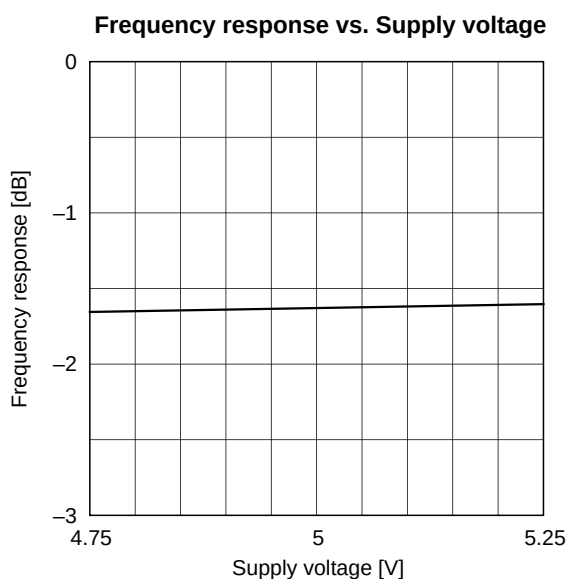
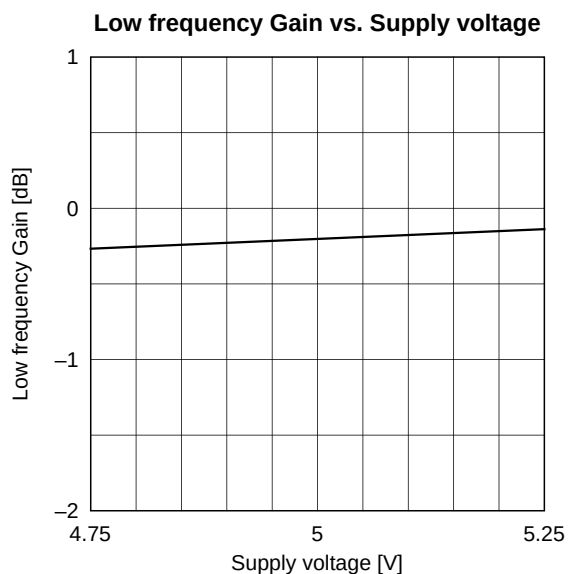
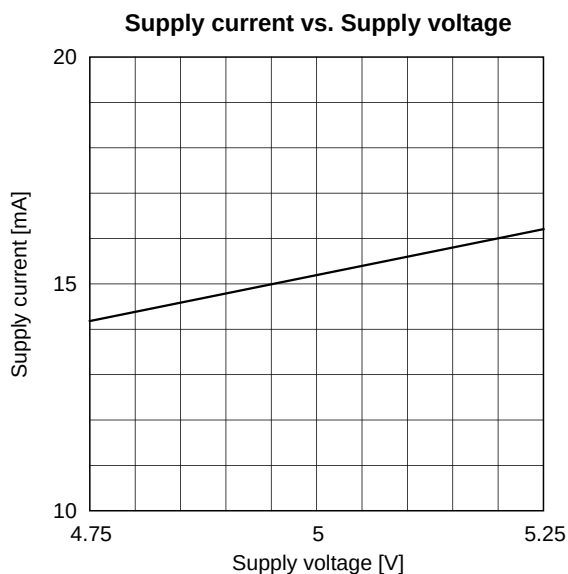


Electrical Characteristics Test Circuit

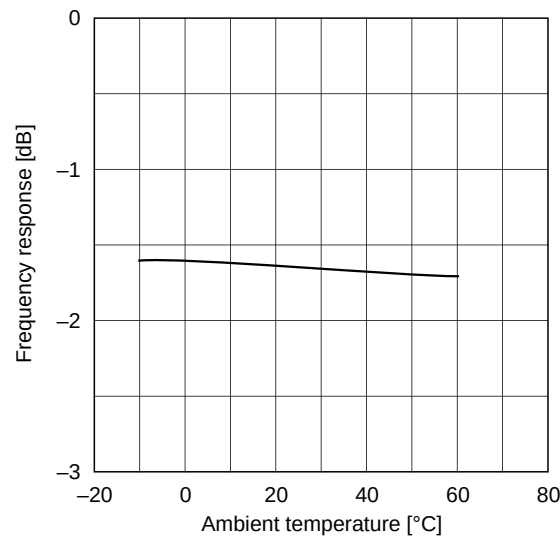




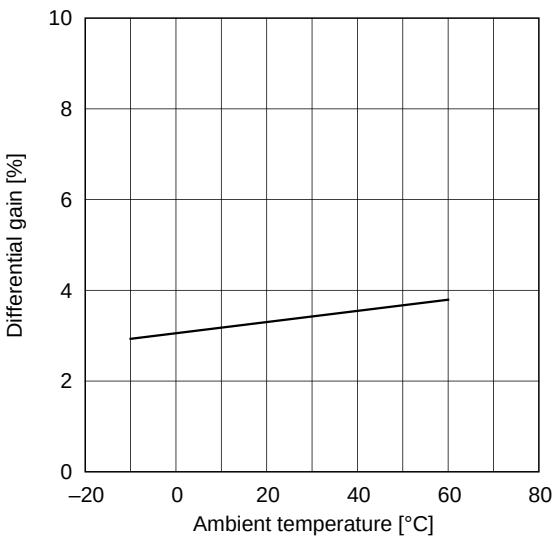
Example of Representative Characteristics



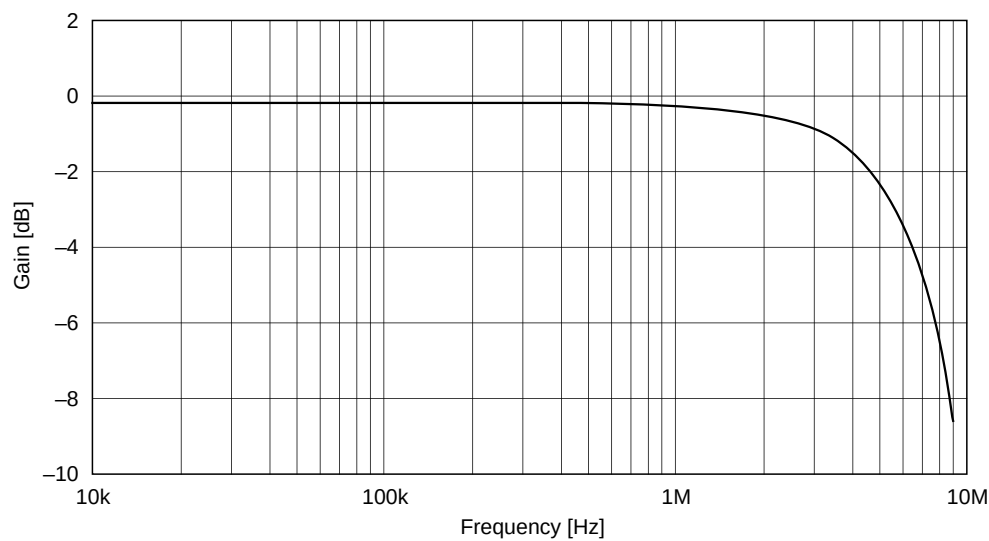
Frequency response vs. Ambient temperature



Differential gain vs. Ambient temperature



Frequency response

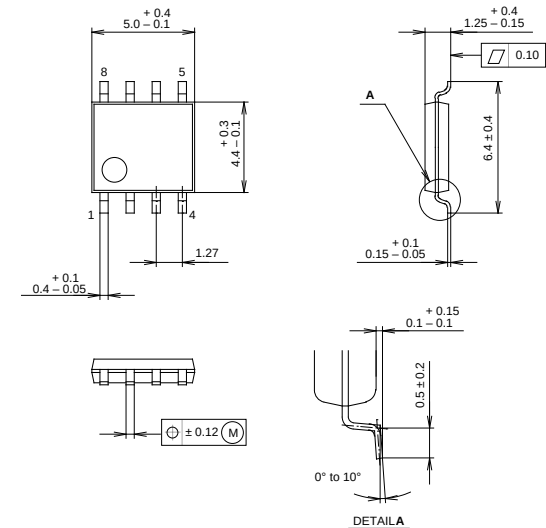


Package Outline

Unit : mm

CXL5514M

8PIN SOP (PLASTIC)



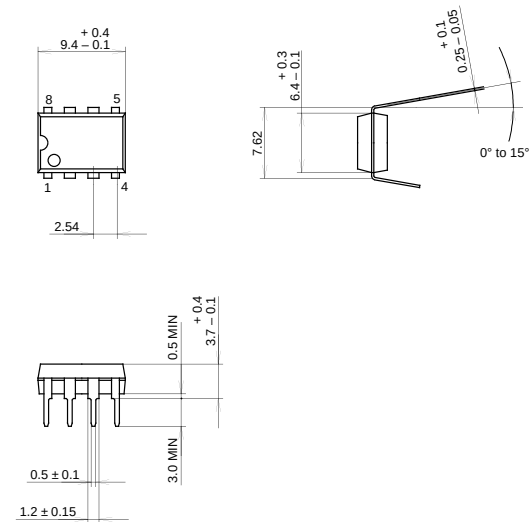
PACKAGE STRUCTURE

SONY CODE	SOP-8P-L03
EIAJ CODE	*SOP008-P-0225-A
JEDEC CODE	—————

MOLDING COMPOUND	EPOXY / PHENOL RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	0.1g

CXL5514P

8PIN DIP (PLASTIC) 300mil



PACKAGE STRUCTURE

SONY CODE	DIP-8P-01
EIAJ CODE	*DIP008-P-0300-A
JEDEC CODE	—————

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE WEIGHT	0.5g